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June 2014

# **FQA70N15**

# N-Channel QFET® MOSFET

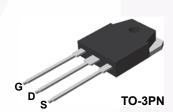
**150 V, 70 A, 28 m**Ω

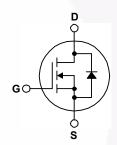
# Description

This N-Channel enhancement mode power MOSFET is produced Fairchild using Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched • 175°C Maximum Junction Temperature Rating mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

## **Features**

- 70 A, 100 V,  $R_{DS(on)}$  = 28 m $\Omega$  (Max)@ $V_{GS}$  = 10 V,  $I_D$  = 35 A
- Low Gate Charge (Typ. 135 nC)
- Low Crss (Typ.135 pF)
- · 100% Avalanche Tested





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

| Symbol                            | Parameter   |          | FQA70N15    | Unit |
|-----------------------------------|---|----------|-------------|------|
| $V_{DSS}$                         | Drain-Source Voltage  |          | 150         | V    |
| l <sub>D</sub>                    | Drain Current - Continuous (T <sub>C</sub> = 25°C                             | C)       | 70          | Α    |
|                                   | - Continuous (T <sub>C</sub> = 100°   | °C)      | 50          | A    |
| I <sub>DM</sub>                   | Drain Curent - Pulsed   | (Note 1) | 280         | А    |
| $V_{GSS}$                         | Gate-Source Voltage   |          | ± 25        | V    |
| E <sub>AS</sub>                   | Single Pulsed Avalanche Energy  | (Note 2) | 1000        | mJ   |
| I <sub>AR</sub>                   | Avalanche Current   | (Note 1) | 70          | Α    |
| E <sub>AR</sub>                   | Repetitive Avalanche Energy   | (Note 1) | 33          | mJ   |
| dv/dt                             | Peak Diode Recovery dv/dt   | (Note 3) | 6.0         | V/ns |
| $P_{D}$                           | Power Dissipation (T <sub>C</sub> = 25°C)                                     |          | 330         | W    |
|                                   | - Derate above 25°C   |          | 2.2         | W/°C |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Temperature Range                                       |          | -55 to +175 | °C   |
| T <sub>L</sub>                    | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds |          | 300         | °C   |

# **Thermal Characteristics**

| Symbol          | Parameter                                     | FQA70N15 | Unit |  |
|-----------------|---|----------|------|--|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case, Max.    | 0.45     | °C/W |  |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient, Max. | 40       | °C/W |  |

# **Package Marking and Ordering Information**

| Device Marking | Device   | Package | Reel Size | Tape Width | Quantity |  |
|----------------|----------|---------|-----------|------------|----------|--|
| FQA70N15       | FQA70N15 | TO-3PN  | -         | -          | 30       |  |

| Symbol                                  | Parameter   | Test Conditions                                 | Min | Тур   | Max   | Uni  |
|---|---|---|-----|-------|-------|------|
| Off Cha                                 | aracteristics   |   |     |       |       |      |
| BV <sub>DSS</sub>                       | Drain-Source Breakdown Voltage                        | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$   | 150 |       |       | V    |
| ΔBV <sub>DSS</sub><br>/ ΔT <sub>J</sub> | Breakdown Voltage Temperature<br>Coefficient          | $I_D$ = 250 $\mu$ A, Referenced to 25°C         |     | 0.15  |       | V/°C |
| I <sub>DSS</sub>                        | Zero Gate Voltage Drain Current                       | V <sub>DS</sub> = 150 V, V <sub>GS</sub> = 0 V  |     |       | 1     | μА   |
|   |   | V <sub>DS</sub> = 120 V, T <sub>C</sub> = 150°C |     |       | 10    | μA   |
| I <sub>GSSF</sub>                       | Gate-Body Leakage Current, Forward                    | V <sub>GS</sub> = 25 V, V <sub>DS</sub> = 0 V   |     |       | 100   | nA   |
| I <sub>GSSR</sub>                       | Gate-Body Leakage Current, Reverse                    | V <sub>GS</sub> = -25 V, V <sub>DS</sub> = 0 V  |     |       | -100  | nA   |
| On Cha                                  | aracteristics   |   |     | 1     |       |      |
| V <sub>GS(th)</sub>                     | Gate Threshold Voltage                                | $V_{DS} = V_{GS}$ , $I_D = 250 \mu A$           | 2.0 |       | 4.0   | V    |
| R <sub>DS(on)</sub>                     | Static Drain-Source<br>On-Resistance                  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 35 A   |     | 0.023 | 0.028 | Ω    |
| 9 <sub>FS</sub>                         | Forward Transconductance                              | V <sub>DS</sub> = 40 V, I <sub>D</sub> = 35 A   |     | 48    |       | S    |
|   | ic Characteristics                                    |   |     |       | 1     |      |
| C <sub>iss</sub>                        | Input Capacitance                                     | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$  |     | 4150  | 5400  | pF   |
| C <sub>oss</sub>                        | Output Capacitance                                    | f = 1.0 MHz                                     |     | 840   | 1100  | pF   |
| C <sub>rss</sub>                        | Reverse Transfer Capacitance                          |   |     | 135   | 175   | pF   |
| Switchi                                 | ing Characteristics                                   |   |     |       |       |      |
| t <sub>d(on)</sub>                      | Turn-On Delay Time                                    | V <sub>DD</sub> = 75 V, I <sub>D</sub> = 70 A,  |     | 60    | 130   | ns   |
| t <sub>r</sub>                          | Turn-On Rise Time                                     | $R_G = 25 \Omega$                               |     | 420   | 850   | ns   |
| t <sub>d(off)</sub>                     | Turn-Off Delay Time                                   | - 1.G 2012                                      |     | 340   | 690   | ns   |
| t <sub>f</sub>                          | Turn-Off Fall Time                                    | (Note 4)  |     | 290   | 590   | ns   |
| Qg                                      | Total Gate Charge                                     | V <sub>DS</sub> = 120 V, I <sub>D</sub> = 70 A, | /   | 135   | 175   | nC   |
| Q <sub>gs</sub>                         | Gate-Source Charge                                    | V <sub>GS</sub> = 10 V                          |     | 25    |       | nC   |
| Q <sub>gd</sub>                         | Gate-Drain Charge                                     | (Note 4)  | /   | 65    |       | nC   |
| Drain-S                                 | Source Diode Characteristics a                        | nd Maximum Ratings                              | •   |       |       |      |
| I <sub>S</sub>                          | Maximum Continuous Drain-Source Diode Forward Current |   |     |       | 70    | Α    |
| I <sub>SM</sub>                         | Maximum Pulsed Drain-Source Diode Forward Current     |   |     |       | 280   | Α    |
| $V_{SD}$                                | Drain-Source Diode Forward Voltage                    | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 70 A    |     |       | 1.5   | V    |
| t <sub>rr</sub>                         | Reverse Recovery Time                                 | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 70 A,   |     | 150   | //    | ns   |
| Q <sub>rr</sub>                         | Reverse Recovery Charge                               | dI <sub>F</sub> / dt = 100 A/μs                 |     | 0.67  |       | иC   |

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 0.34mH,  $I_{AS} = 70\text{A}$ ,  $V_{DD} = 25\text{V}$ ,  $R_{C} = 25\,\Omega$ , Starting  $T_{J} = 25^{\circ}\text{C}$  3.  $I_{SD} \leq 70\text{A}$ ,  $di/dt \leq 300\text{A}/\mu\text{s}$ ,  $V_{DD} = BV_{DSS}$ , Starting  $T_{J} = 25^{\circ}\text{C}$  4. Essentially independent of operating temperature

# **Typical Characteristics**

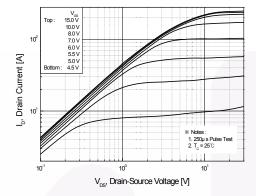


Figure 1. On-Region Characteristics

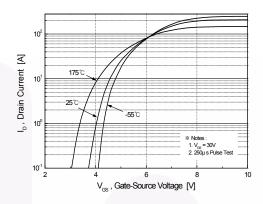


Figure 2. Transfer Characteristics

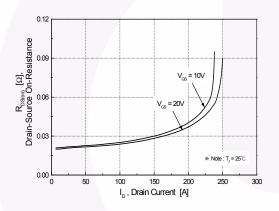


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

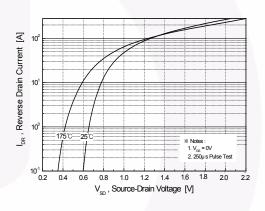


Figure 4. Body Diode Forward Voltage Variation vs. Source Current

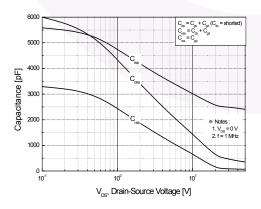


Figure 5. Capacitance Characteristics

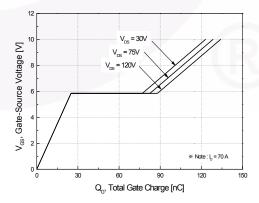


Figure 6. Gate Charge Characteristics

# Typical Characteristics (Continued)

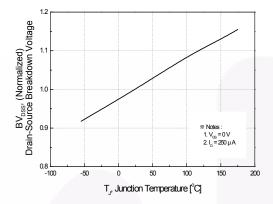


Figure 7. Breakdown Voltage Variation vs. Temperature

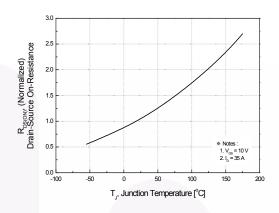


Figure 8. On-Resistance Variation vs. Temperature

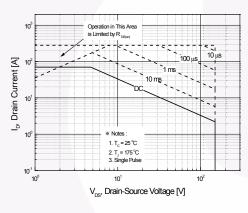


Figure 9. Maximum Safe Operating Area

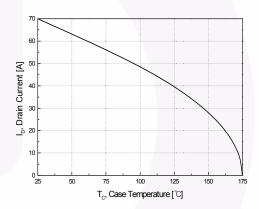


Figure 10. Maximum Drain Current vs. Case Temperature

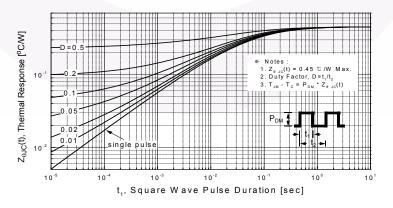


Figure 11. Transient Thermal Response Curve



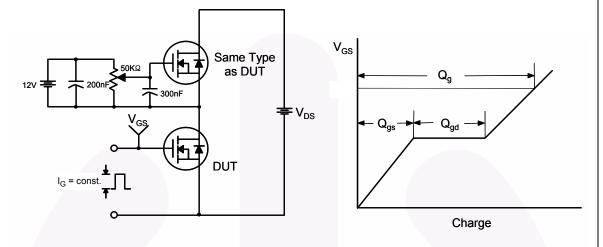


Figure 13. Resistive Switching Test Circuit & Waveforms

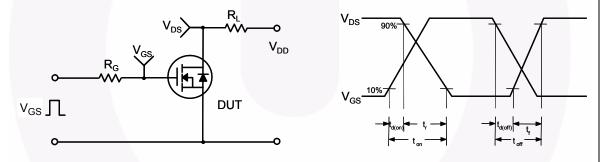
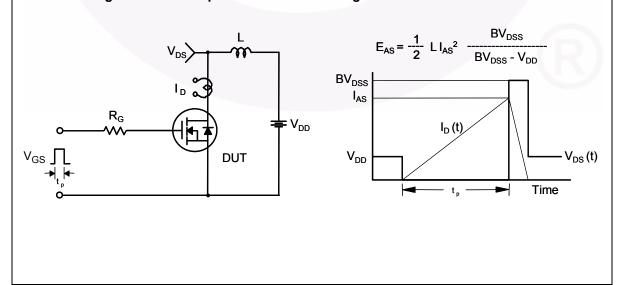
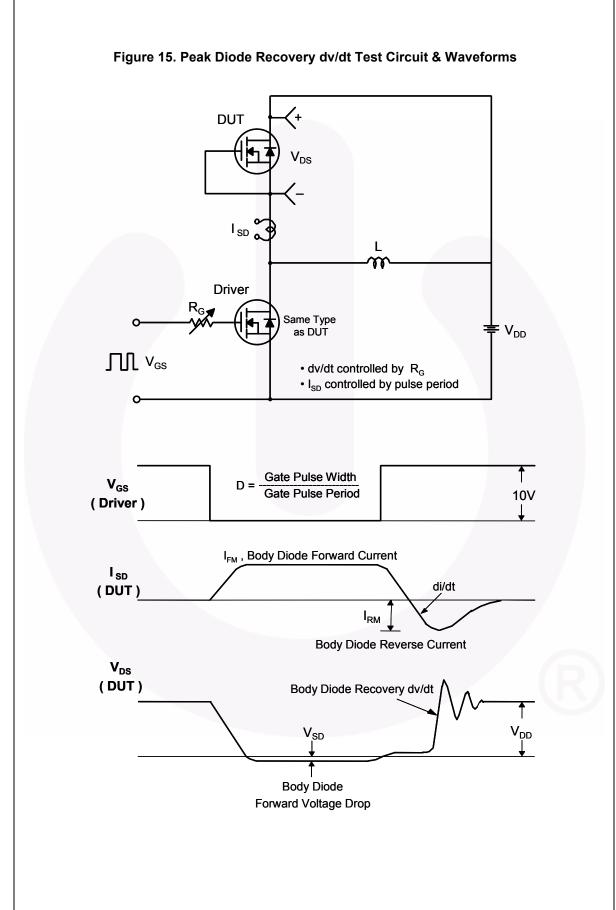


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms





# **Mechanical Dimensions**

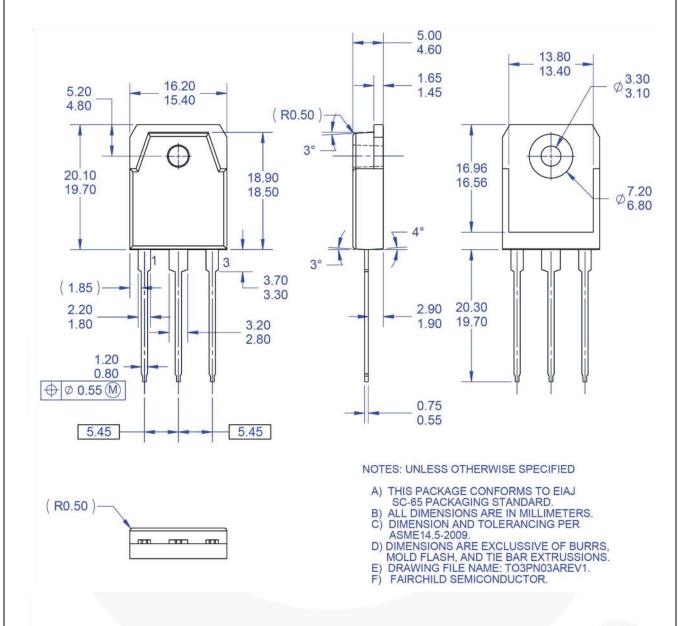


Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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